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No. <u>09/663,417</u> .
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Application/Control Number: 10/750,823

Art Unit: 3723

REASONS FOR ALLOWANCE

The following is an examiner's statement of reasons for allowance: the specific limitations of "a dummy wafer station for holding at least one dummy wafer" in the combination as claimed in claim 1; "a transporter for handling a plurality of the wafers at one time, and for moving a wafer to a preferable position below a top ring which holds the wafer during polishing operation" in the combination as claimed in claim 6; and "wherein a pressure of a space in which said cleaning and drying unit are disposed is adjusted so as to be lower than a pressure of a space in which said load-unload stages are disposed" in the combination as claimed in claim 13, are not anticipated or made obvious by the prior art in the examiner's opinion. For example, Shimizu et al. (5,989,107) disclose a polishing apparatus for polishing comprising at least three loadunloaded stages (21) for placing a wafer cassette which accommodates a plurality of wafers (fig.1); a polishing unit (10) for polishing a plurality of wafers simultaneously (col. 6, lines 46-48), cleaning unit (23a-23c) for cleaning the polished wafer. Shimizu et al. disclose robots (22a, 22b) and the cleaning unit are disposed between the loadingunload stages and the polishing unit. However, the art of record considered as a whole, alone or in combination fails to provide or suggest "a dummy wafer station for holding at least one dummy wafer; a transporter for handling a plurality of the wafers at one time, and for moving a wafer to a preferable position below a top ring which holds the wafer during polishing operation; and wherein a pressure of a space in which said cleaning and drying unit are disposed is adjusted so as to be lower than a pressure of a space in which said load-unload stages are disposed".

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Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Anthony Ojini whose telephone number is 571 272 4492. The examiner can normally be reached on 7 to 4 Tuesday-Friday with every other Monday off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Joseph Hail can be reached on 571 272 4485. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Joseph J. Hail, III Supervisory Patent Examiner Technology Center 3700

Jul J. Halt

AO 11/27/04